CALL FOR PAPERS

ABOUT EPTC

The 19th Electronics Packaging Technology Conference (EPTC 2017) is an International event organized by the IEEE Reliability/CPMT/ED Singapore Chapter and sponsored by IEEE CPMT Society.

EPTC 2017 will feature technical sessions, professional development courses, forums, an exhibition, social and networking activities. It aims to provide a good coverage of technological develop-ments in all areas of electronics packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in Asia and is well attended by experts in all aspects related to packaging technology from all over the world. EPTC is the flagship conference of the IEEE CPMT Society in Region 10.

CONFERENCE TOPICS

You are invited to submit an abstract, presenting new developments in the following categories:

- **Advanced Packaging:** advanced flip-chip, 2.5D & 3D, PoP, embedded passives & actives on substrates, System in Package, embedded chip packaging technologies, panel level packaging, RF, Microwave & Millimeter-wave, power and Rugged Electronics Packaging etc.
- **TSV/Wafer Level Packaging:** wafer level packaging (Fan In/Fan Out), embedded chip packaging, 2.5D/3D integration, TSV, silicon & glass interposers, RDL, bumping technologies, etc.
- **Interconnection Technologies:** Au/Ag/Cu/Al wire-bond / wedge bond technology, flip-chip & Cu pillar, solder alternatives (ICP, ACP, ACF, NCP, ICA), Cu to Cu, wafer level bonding & die attachment (Pb-free) etc.
- **Emerging Technologies:** packaging technologies for MEMS, biomedical, optoelectronics, internet of things, photovoltaic, printed electronics, wearable electronics, photonics, LED, etc.
- **Materials and Processing:** advanced materials, 3D materials, photoresists, polymer dielectrics, solder materials, die attach, underfill, substrates, leadframes, PCB etc for advanced packaging, and assembly processes using advanced materials, etc.
- **Equipment and Process Automation:** new processes development, equipment automation, equipment hardware development/improvements, data analytics, in-situ metrology, etc.
- **Electrical Simulations & Characterization:** Power plane modeling, signal integrity analysis of package. 2D/2.5D/3D package level high-speed signal design, characterization and test methodologies, etc.
- **Mechanical Modeling & Simulations:** thermo-mechanical, moisture, fracture, fatigue, vibration, shock and drop impact modeling, chip-package interaction, reliability, virtual prototyping, etc.
- **Thermal Characterization & Cooling Solutions:** thermal modeling and simulation, component, system and product level thermal management and characterization.
- **Quality, Reliability & Failure Analysis:** component, board, system and product level reliability assessment, interfacial adhesion, accelerated testing, failure characterization, etc.

Others are also welcomed, e.g. market trends, environmental issues, legislation, patents, education, cost analysis, etc.

IMPORTANT DATES

Online abstract submission start	31st Mar 2017
Closing of abstract submission	15th June 2017
Notification of acceptance	15th July 2017
Submission of manuscript	15th September 2017

ABSTRACT AND PAPER SUBMISSION

Abstracts are solicited which describe original and unpublished work. The abstract should be at least 500-750 words and must clearly state the purpose, methodology, results (including data, figures, graphs and photographs) and conclusions of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well. Authors can choose between oral or interactive presentation but the decision of the Organising Committee will be final. Only accepted papers which are presented (oral & interactive) in the conference will be published in the conference proceedings and in IEEE Xplore.

Authors must designate two appropriate categories (found under CONFERENCE TOPICS) for abstract review. All submissions must be in English and should be made via the online submission system found at http://www.eptc-ieee.net. The required file format is Adobe Acrobat® PDF or MS Word in one single file for each submission.

The abstracts must be received by 15th June 2017. Authors must include their affiliation, mailing address, telephone, and email address. Authors will be notified of paper acceptance and publication instructions by 15th July 2017. The final manuscript for publication in the conference proceedings and the presenter's registration are due on 15th September 2017.

OUTSTANDING TECHNICAL PAPERS

Author(s) of Best Technical Paper (oral/interactive), Outstanding Technical Paper (oral) and Best Student Paper will receive an award at the next conference. More details can be found at http://www.eptc-ieee.net.

CALL FOR PROFESSIONAL DEVELOPMENT COURSES

The conference program includes professional development courses (PDCs) which will be conducted by leading experts in the field. Details, when available, will be updated in the conference website. Proposals for PDCs can be submitted to pdc@eptc-ieee.net as soon as possible.

CALL FOR EXHIBITION/SPONSORSHIP PARTICIPATION

A tabletop exhibition featuring suppliers of materials, equipment, software and service providers of microelectronics and electronic assembly industries, will be held during the conference. Potential exhibitors and sponsors may email exhibition@eptc-ieee.net and sponsorship@eptc-ieee.net for details.

EPTC 2017: website: http://www.eptc-ieee.net Email: secretariat@eptc-ieee.net
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Organized by IEEE
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